

ABSTRACT

A new design is provided for the design of a leadframe of a semiconductor package. A ground plane is added to the design of the leadframe, the ground frame is located between the leadframe and the die attach paddle over which the semiconductor device is mounted.

1. A leadframe for a semiconductor package, comprising:
a. a die attach paddle;
b. a ground plane located between the die attach paddle and the leadframe;
c. a leadframe body located between the ground plane and the leadframe;
d. a leadframe body located between the ground plane and the leadframe;
e. a leadframe body located between the ground plane and the leadframe;
f. a leadframe body located between the ground plane and the leadframe;
g. a leadframe body located between the ground plane and the leadframe;
h. a leadframe body located between the ground plane and the leadframe;
i. a leadframe body located between the ground plane and the leadframe;
j. a leadframe body located between the ground plane and the leadframe;
k. a leadframe body located between the ground plane and the leadframe;
l. a leadframe body located between the ground plane and the leadframe;
m. a leadframe body located between the ground plane and the leadframe;
n. a leadframe body located between the ground plane and the leadframe;
o. a leadframe body located between the ground plane and the leadframe;
p. a leadframe body located between the ground plane and the leadframe;
q. a leadframe body located between the ground plane and the leadframe;
r. a leadframe body located between the ground plane and the leadframe;
s. a leadframe body located between the ground plane and the leadframe;
t. a leadframe body located between the ground plane and the leadframe;
u. a leadframe body located between the ground plane and the leadframe;
v. a leadframe body located between the ground plane and the leadframe;
w. a leadframe body located between the ground plane and the leadframe;
x. a leadframe body located between the ground plane and the leadframe;
y. a leadframe body located between the ground plane and the leadframe;
z. a leadframe body located between the ground plane and the leadframe;